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(12) **United States Design Patent**
Lin et al.

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(54) **THERMAL MODULE**

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(**) Term: **14 Years**

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(22) Filed: **Dec. 31, 2003**

(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/179**

(58) **Field of Search** D13/179; 165/80.3,
165/121, 122, 146, 104.33, 180, 185; 174/16.3;
257/706, 707, 718-722; 361/271, 274.3,
695, 697, 700, 702, 704, 709, 710, 711,
514, 719

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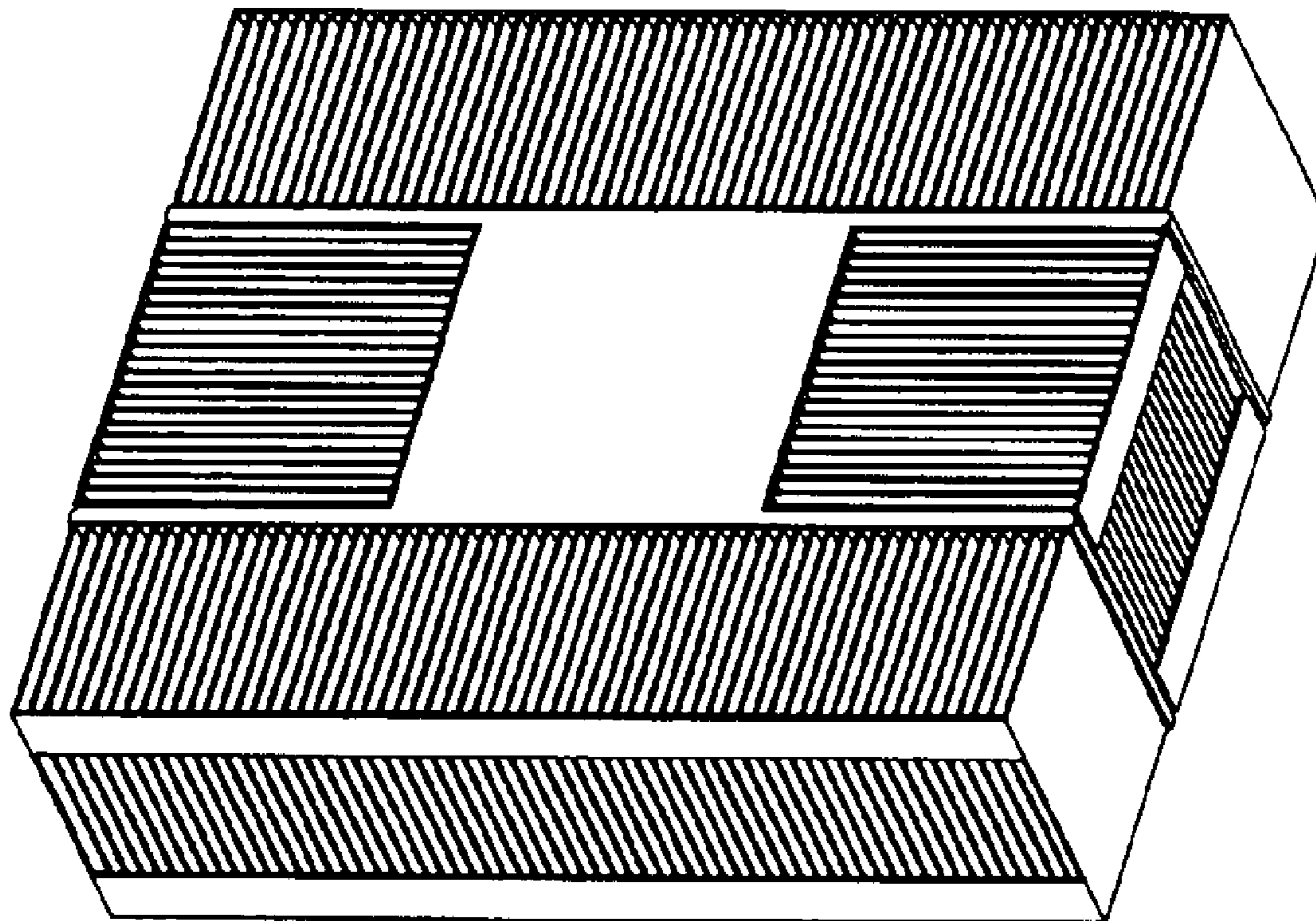
(57) **CLAIM**

The ornamental design for a thermal module, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a thermal module showing our new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a right side elevational view thereof;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof; and,
FIG. 7 is a rear elevational view thereof.

1 Claim, 7 Drawing Sheets



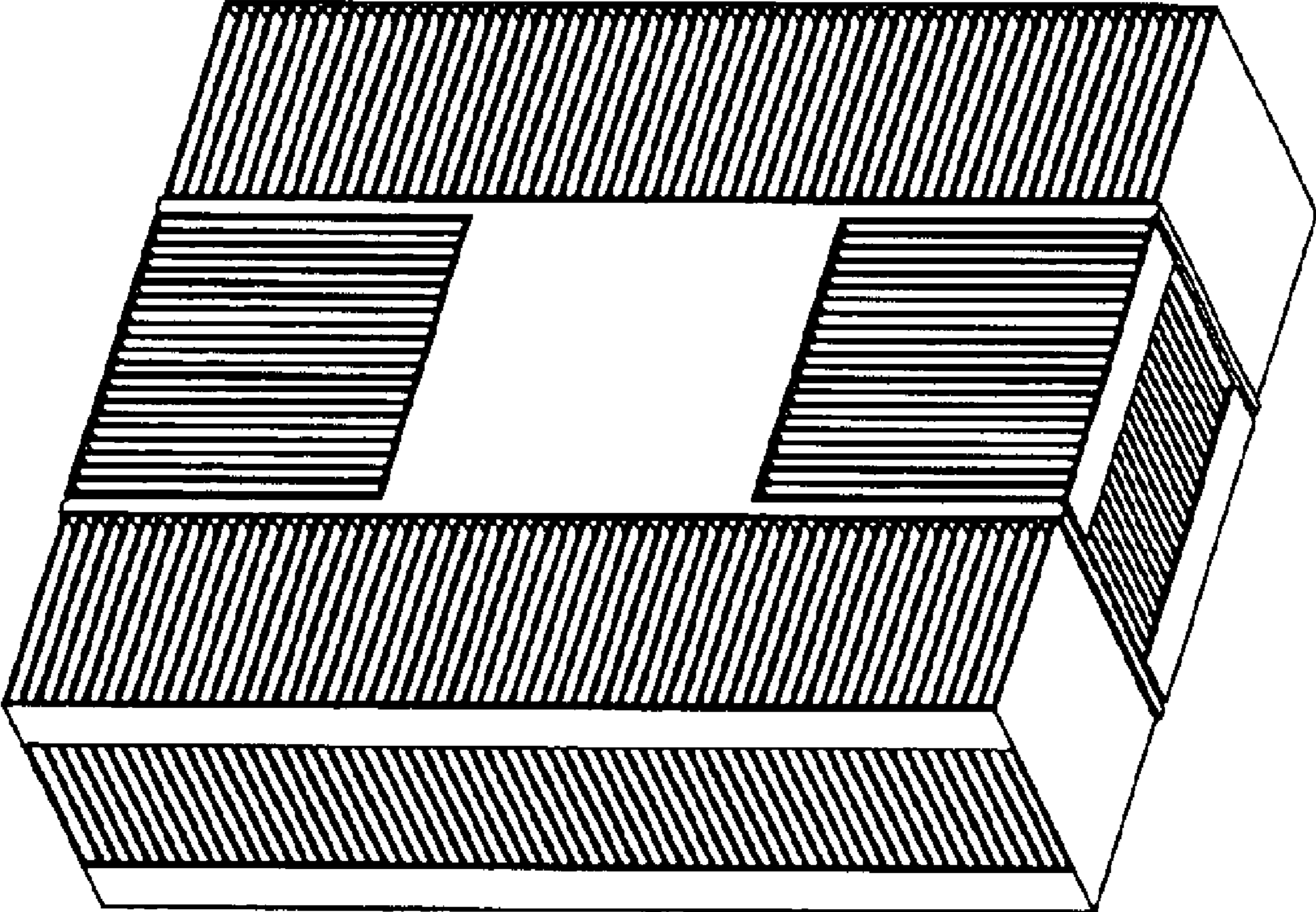


FIG. 1

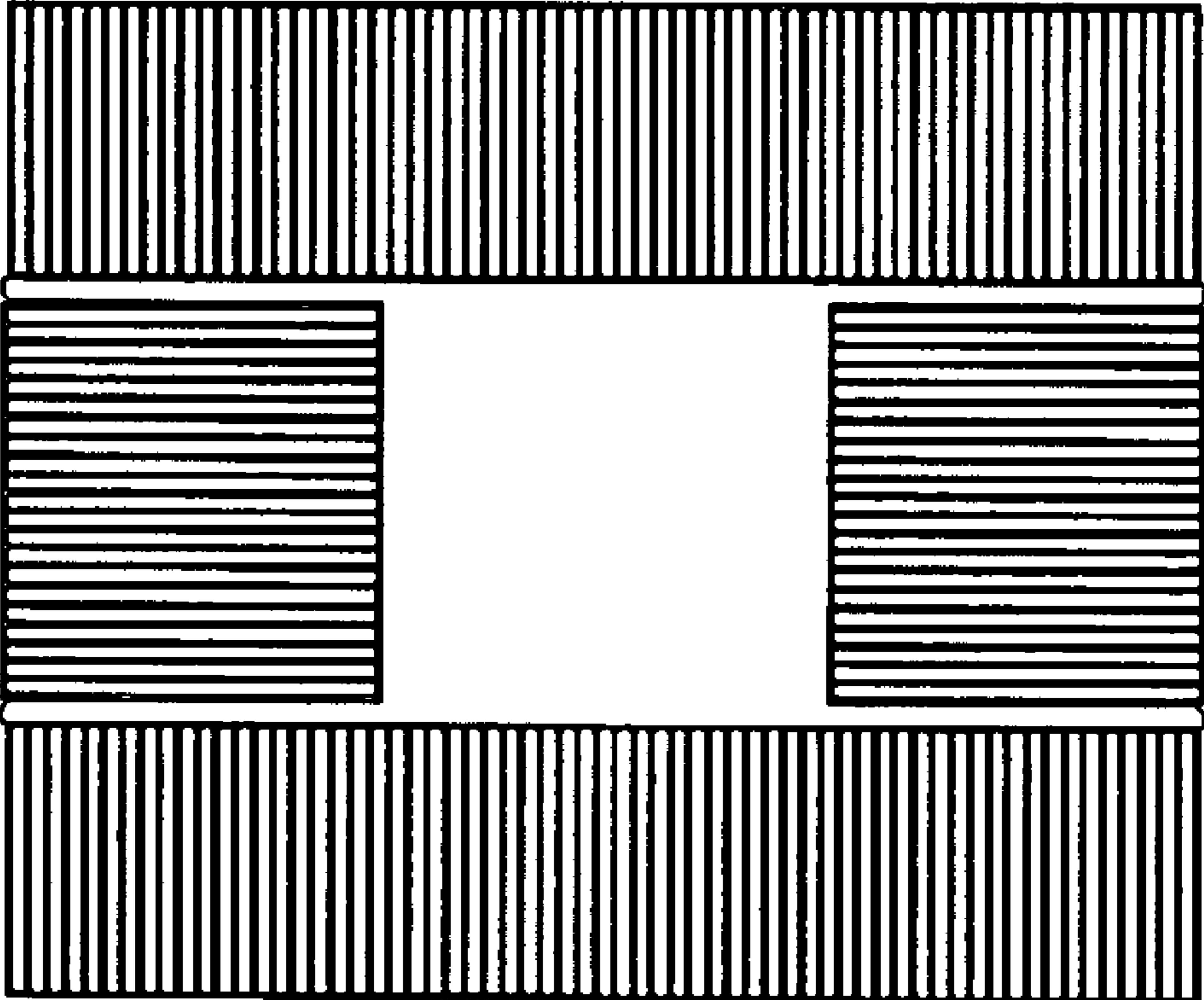


FIG. 2

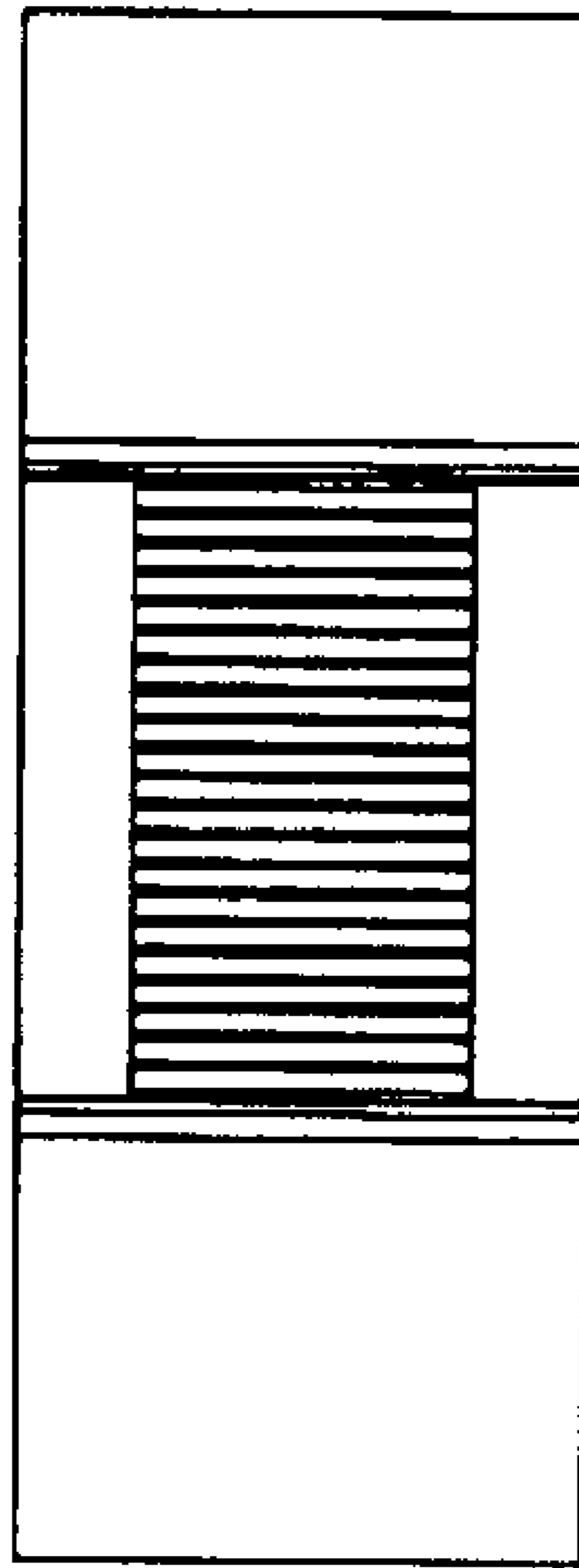


FIG. 3

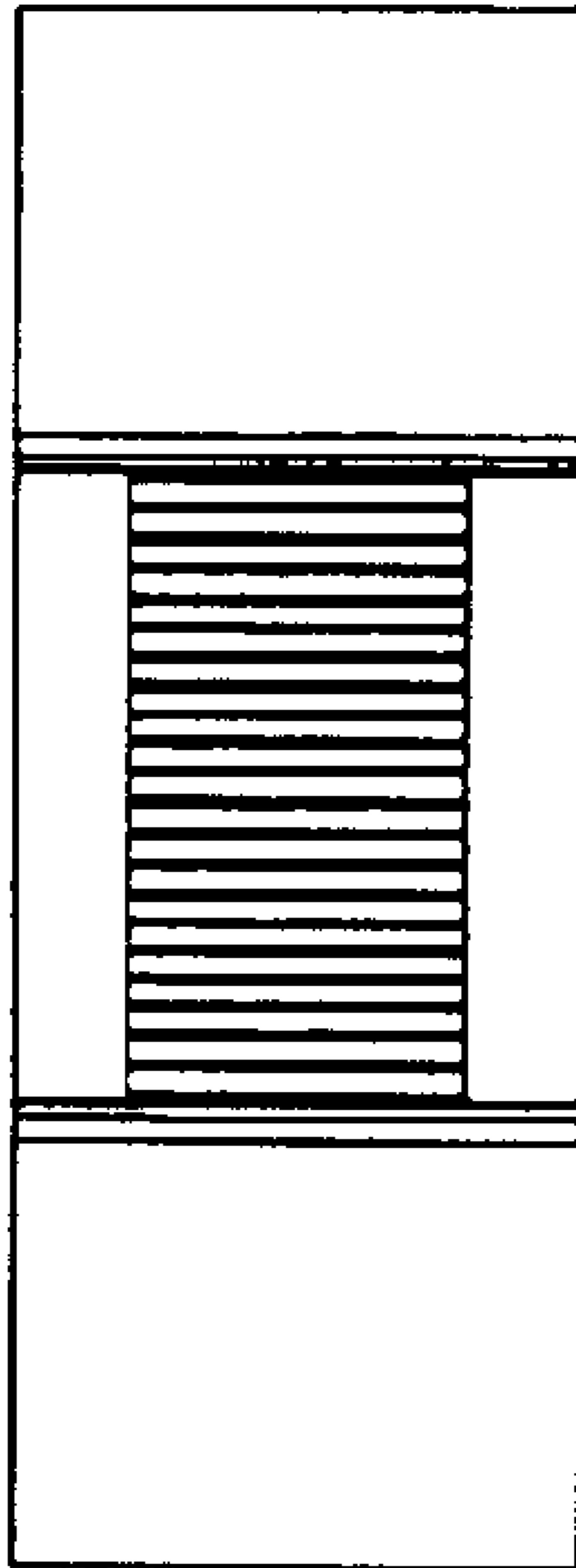


FIG. 4

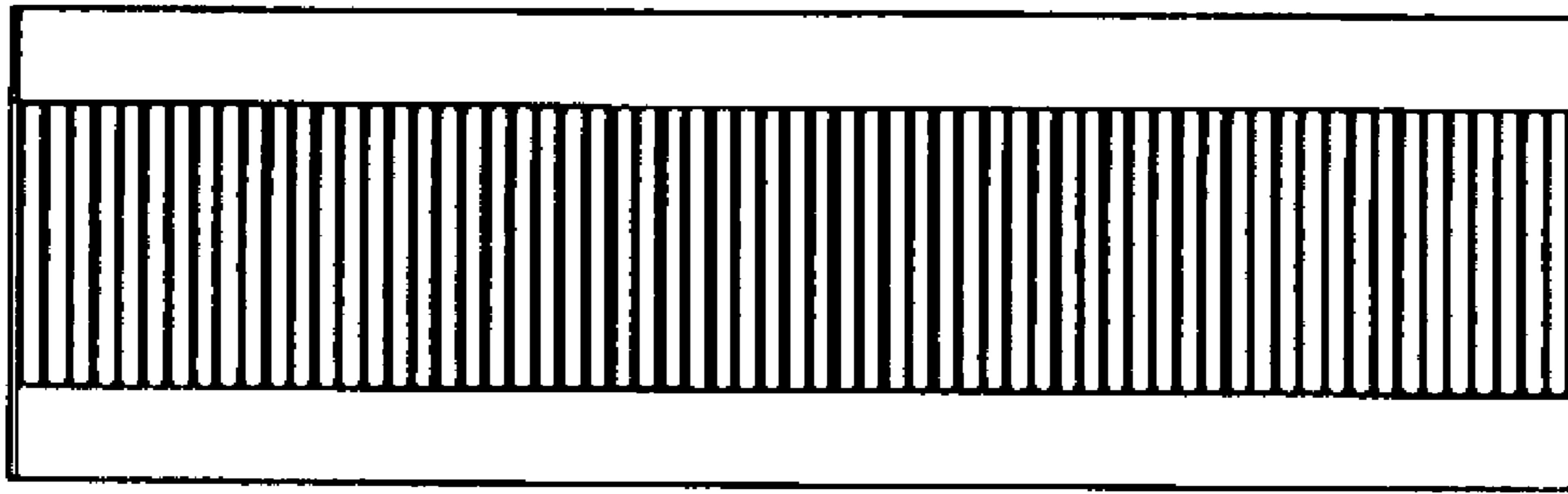


FIG. 5

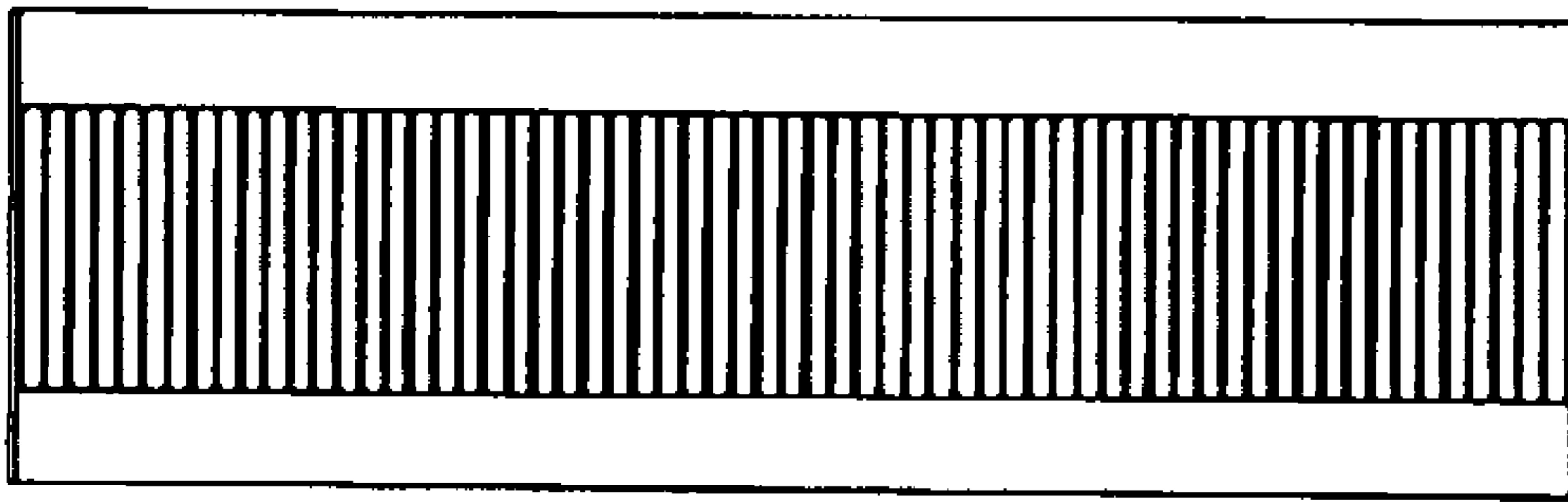


FIG. 6

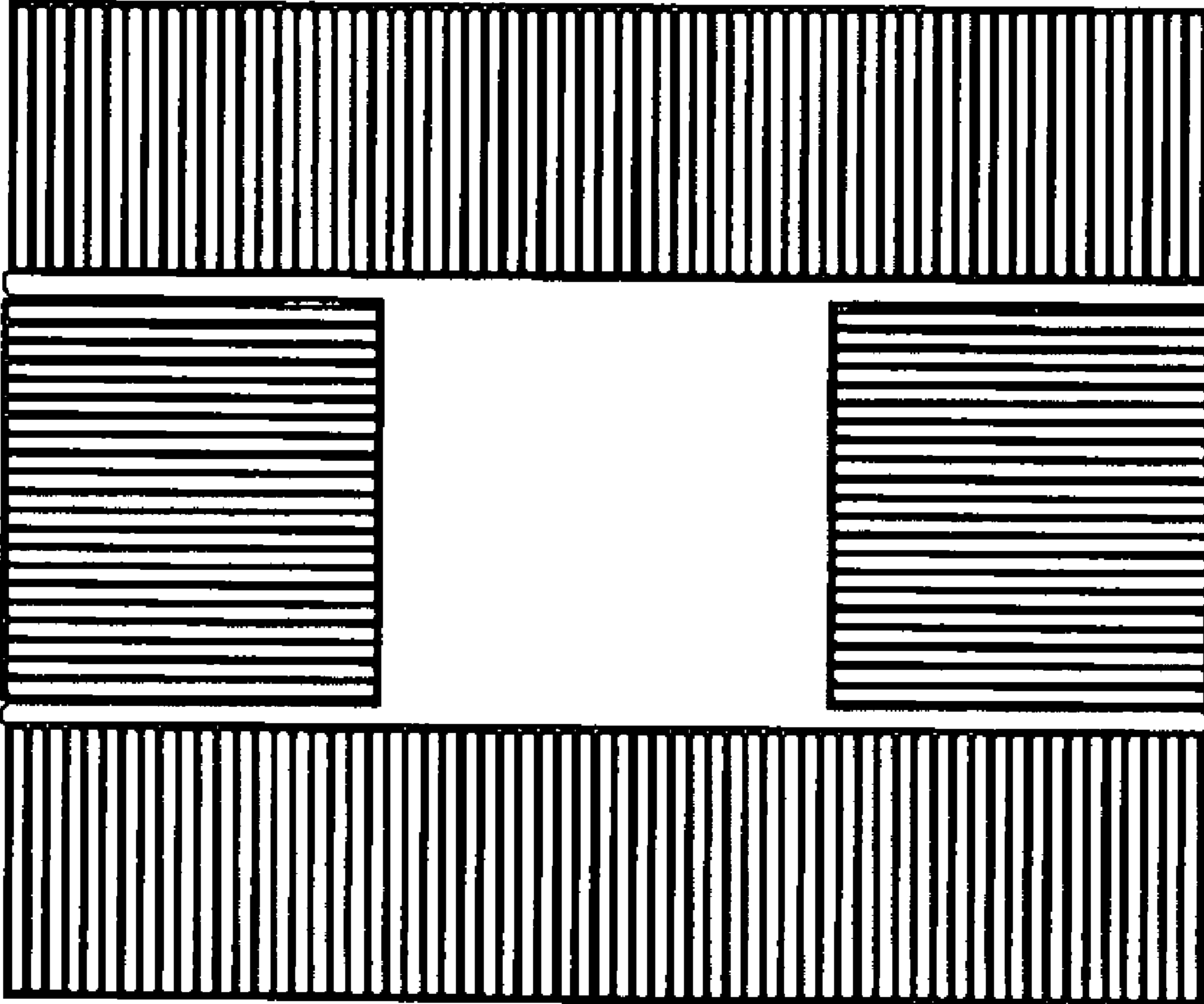


FIG. 7